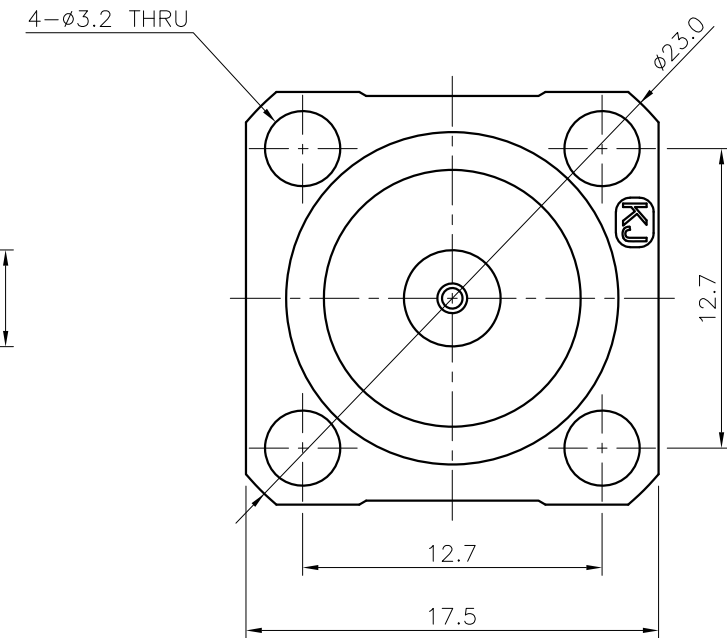
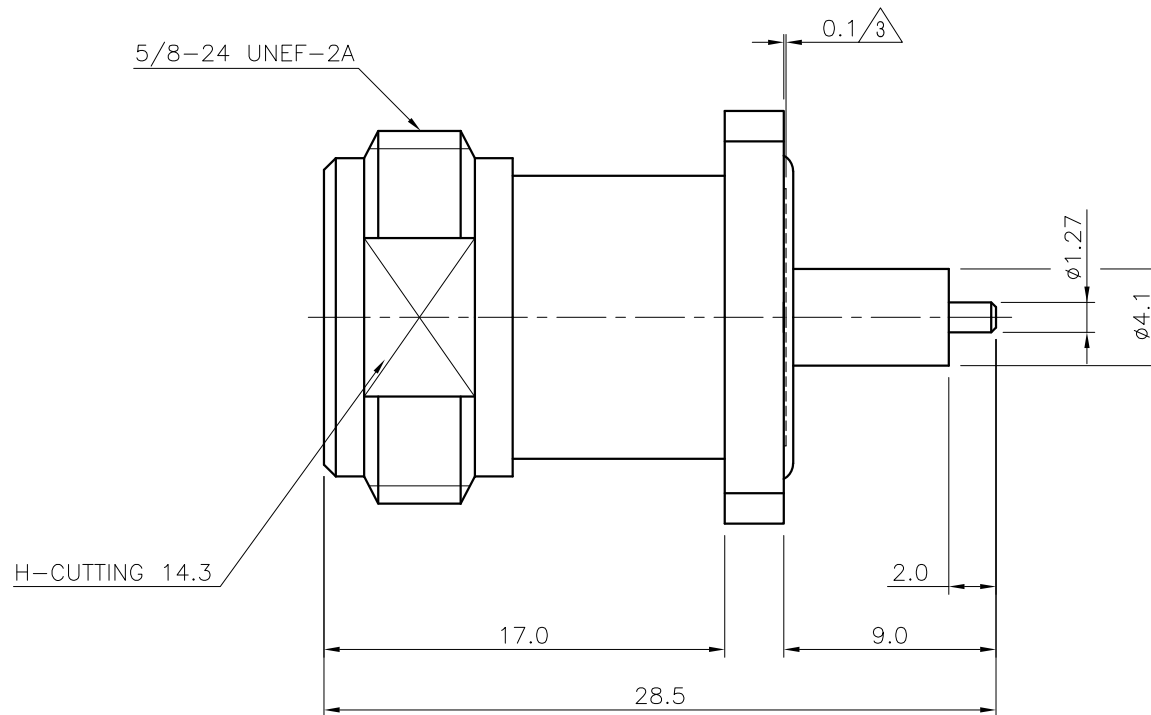


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.09.03.
1	[설변No.201907-0003] 가스켓 이탈 개선으로 인한 코드변경	S.Y.EUN	I.C.KIM	2019.07.02.
2	[설변No.202012-0002] O-RING 빠짐 개선 안착부 금형수정	I.C.KIM		2020.12.07.
3	[설변No.202101-0003] O-RING 빠짐 개선 안착부 0.1mm Ground Boss 추가	S.Y.EUN	I.C.KIM	2021.01.20.
4	RING 억지끼움후 돌출부위 감안하여 길이 조정	S.H.KIM		2024.11.08.



1	5	GASKET	1	SILICONE RUB	RED	DGK00257-N/2 DGK00032-N/1
4	4	RING	1	MBsBD C3604BD-F	Nickel Plate	DSR01097-5/4 DSR01097-5/3
3	3	INSULATOR	1	TEFLON		DIN02840-N/3
2	2	CONTACT	1	BeCu C17300	Gold Plate	DCT03768-5/3
2	1	BODY	1	ZnDC	Nickel Plate (3~4µm)	DBD02992-5/3 DBD02992-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 11. 08.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY				
MATERIAL _____		CHECKED BY			TITLE N50 SOLDER END JS-4H	
		DRAWN BY S.H.KIM				
FINISH _____		SCALE 3/1	UNIT mm		A4	
						DWG NO. CN03958-7/4
					REVISION 4	SHEET 1 of 1